

IN THE CLAIMS:

Claims 9, 10, 14, 15 18 and 20 through 22 have been amended herein. New claims 42 through 45 have been added. Please note that all claims currently pending and under consideration in the referenced application are shown below, in clean form, for clarity. Please enter these claims as amended. Also attached is a version with markings to show changes made to the claims.

✓
Please cancel claims 1 through 8, 19 and 24 through 41 without prejudice or disclaimer.

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9. (Amended) A device for establishing electrical contact with a lead element extending from an IC device, comprising:
a substrate configured for operably connecting said IC device to at least one other IC device mounted on said substrate or at least one electrical component mounted on said substrate;
a spring contact including a base portion and a contact portion, said contact portion comprising a resiliently compressible coil spring configured to bias against and electrically contact said lead element of said IC device; and
an aperture including a seat portion opening onto one surface of said substrate and a retaining portion having a first end connected to an opposing end of said seat portion and a second end extending a depth at least partially into said substrate, said seat portion of said aperture configured to at least partially contain said contact portion of said spring contact and said retaining portion of said aperture configured to receive and electrically contact said base portion of said spring contact.

10. (Amended) The device of claim 9, wherein said second end of said retaining portion does not extend entirely through said substrate.

11. The device of claim 9, further comprising a layer of conductive material disposed on at least a portion of an interior wall of said aperture, said layer of conductive material electrically contacting said base portion of said spring contact.

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12. The device of claim 11, wherein said layer of conductive material is electrically connected to a conductive trace formed on said one surface of said substrate.

13. The device of claim 11, wherein said layer of conductive material is electrically connected to an intermediate conductive plane of said substrate.

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14. (Amended) The device of claim 11, wherein said retaining portion of said aperture extends through said substrate and opens onto an opposing surface of said substrate and said layer of conductive material is electrically connected to a conductive trace formed on said opposing surface of said substrate.

15. (Amended) The device of claim 9, further comprising a volume of conductive filler material disposed in and filling at least a partial depth of said aperture and electrically contacting said base portion of said spring contact.

16. The device of claim 15, wherein said conductive filler material is electrically connected to a conductive trace formed on said one surface of said substrate.

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17. The device of claim 15, wherein said conductive filler material is electrically connected to an intermediate conductive plane of said substrate.

~~Sub 7~~
~~B3~~ 18. (Amended) The device of claim 15, wherein said retaining portion of said aperture extends through said substrate and opens onto an opposing surface of said substrate and said conductive filler material is electrically connected to a conductive trace formed on said opposing surface of said substrate.

~~Sub 7~~
~~B4~~ 20. (Amended) The device of claim 9, said second end of said retaining portion opening onto an opposing surface of said substrate.

21. (Amended) The device of claim 9, wherein said seat portion comprises a generally hemispherical recess formed in said one surface of said substrate, a generally conical recess formed in said one surface of said substrate, or a generally cylindrical recess formed in said one surface of said substrate.

22. (Amended) The device of claim 9, wherein said seat portion is further configured to at least partially align said lead element of said IC device relative to said spring contact.

23. (Previously Amended) The device of claim 9, wherein said contact portion of said spring contact comprises a resiliently compressible coil spring having at least two spring coils for contacting portions thereof and configured to bias against and electrically contact said lead element of said IC device. ~~NE~~

Please add the following new claims:

~~B5~~ 42. The device of claim 9, wherein said resiliently compressible coil spring of said contact portion further comprises at least one point for penetrating an outer surface of said lead element of said IC device.

43. The device of claim 9, wherein said resiliently compressible coil spring of said contact portion further comprises a contact element selected from the group consisting of a sharp edge formed by a cross-section of said resiliently compressible coil spring, a blade extending longitudinally along a surface of said resiliently compressible coil spring, a blade extending circumferentially around a surface of said resiliently compressible coil spring or a barb protruding from a surface of said resiliently compressible coil spring.

~~B5~~
~~Sub C7~~ 44. The device of claim 9, further comprising a clamping element configured to secure said IC device to said surface of said substrate.

45. The device of claim 44, wherein said clamping element comprises a stab-in-place clip.
